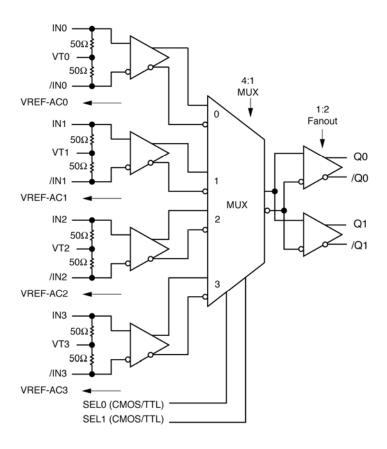
## **Functional Block Diagram**



### **Truth Table**

SEL1	SEL0	Q
0	0	IN0 Input Select
0	1	IN1 Input Select
1	0	IN2 Input Select
1	1	IN3 Input Select

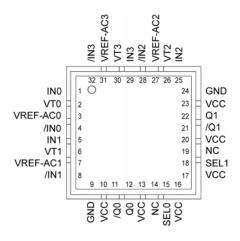
# Ordering Information<sup>(1)</sup>

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY89855UMG	QFN-32	Industrial	SY89855U with Pb-Free bar-line indicator	NiPdAu Pb-Free
SY89855UMGTR <sup>(2)</sup>	QFN-32	Industrial	SY89855U with Pb-Free bar-line indicator	NiPdAu Pb-Free

#### Notes

- 1. Contact factory for die availability. Dice are guaranteed at  $T_A$  = 25°C, DC Electricals only.
- 2. Tape and Reel.

### **Pin Configuration**



32-Pin QFN

## **Pin Description**

Pin Number	Pin Name	Pin Function
1, 4 5, 8 25, 28 29, 32	IN0, /IN0, IN1, /IN1, IN2, /IN2, IN3, /IN3	Differential Input: Each pair accepts AC- or DC-coupled signals as small as 100mV. Each pin of a pair internally terminates to a VT pin through $50\Omega$ . Note that these inputs will default to an indeterminate state if left open. If an input is not used, connect one end of the differential pairs to ground through a $1k\Omega$ resistor, and leave the other end to VCC through an $825\Omega$ resistor. Unused VT and VREF-AC pins may also be left floating. Please refer to the "Input Interface Applications" section for more details.
2, 6 26, 30	VT0, VT1 VT2, VT3	Input Termination Center-Tap: Each side of the differential input pair terminates to a VT pin. The VT pin provides a center-tap to the termination network for maximum interface flexibility. See "Input Interface Applications" section for more details.
15, 18	SEL0, SEL1	This Single-Ended TTL/CMOS compatible input selects the inputs to the multiplexer. Note that this input is internally connected to a $25k\Omega$ pull-up resistor and will default to a logic HIGH state if left open. Input logic threshold is $V_{CC}/2$ . See "Truth Table" for select control.
14, 19	NC	Not connected.
10, 13, 16 17, 20, 23	VCC	Positive Power Supply: Bypass with $0.1\mu F  0.01\mu F $ low ESR capacitors placed as close as possible to each VCC pin.
11, 12 21, 22	/Q0, Q0 /Q1, Q1	Differential Outputs: These 100K-compatible (internally temperature compensated) LVPECL output pairs are copies of the selected input. Unused output pins may be left floating. See "Output Interface" for terminating guidelines.
9, 24	GND, Exposed Pad	Ground: Ground pins and exposed pad must be connected to the most negative potential of the chip.
3 7 27 31	VREF-AC0, VREF-AC1, VREF-AC2, VREF-AC3	Reference Voltage: This reference output is equivalent to $V_{CC}$ –1.2V. It is used for AC-coupled inputs. When interfacing to AC input signals, connect VREF-AC directly to the VT pin and bypass with a $0.01\mu F$ low ESR capacitor to VCC. See "Input Interface Applications" section. Maximum sink/source current is $\pm$ 1.5mA.

# Absolute Maximum Ratings<sup>(1)</sup>

Supply Voltage (V <sub>CC</sub> )	0.5V to +4.0V
Input Voltage (V <sub>IN</sub> )	–0.5V to V <sub>CC</sub>
LVPECL Output Current (I <sub>OUT</sub> )	
Continuous	±50mA
Surge	±100mA
Termination Current	
Source or Sink Current on V <sub>T</sub>	±100mA
Input Current	
Source or Sink Current on IN, /IN.	±50mA
Current (V <sub>REF-AC</sub> )	
Source or Sink Current on V <sub>REF-AC</sub>	±2mA
Lead Temperature (soldering, 20sec.)	260°C
Storage Temperature (T <sub>s</sub> ) –	-65°C to +150°C

# Operating Ratings<sup>(2)</sup>

Supply Voltage (V <sub>CC</sub> )	+2.375V to +2.625V
	+3.0V to +3.6V
Ambient Temperature (T <sub>A</sub> )	40°C to +85°C
Ambient Temperature (T <sub>A</sub> ) Package Thermal Resistance <sup>(3)</sup>	
QFN $(\theta_{JA})$	
Still-Air	35°C/W
500lfpm	28°C/W
QFN (Ψ <sub>JB</sub> )	
Junction-to-Board	16°C/W

## DC Electrical Characteristics<sup>(4)</sup>

 $T_A = -40$ °C to +85°C, unless otherwise noted.

Symbol	Parameter	Condition	Min	Тур	Max	Units
Vcc	Power Supply Voltage	V <sub>CC</sub> = 2.5V V <sub>CC</sub> = 3.3V	2.375 3.0	2.5 3.3	2.625 3.6	V V
I <sub>CC</sub>	Power Supply Current	No load, max. V <sub>CC</sub> .		65	85	mA
R <sub>IN</sub>	Input Resistance (IN-to-VT)		45	50	55	Ω
R <sub>DIFF_IN</sub>	Differential Input Resistance (IN-to-/IN, /IN-to-V <sub>T</sub> )		90	100	110	Ω
V <sub>IH</sub>	Input High Voltage (IN, /IN)	Note 5	V <sub>CC</sub> - 1.6		Vcc	V
V <sub>IL</sub>	Input Low Voltage (IN, /IN)		0		V <sub>IH</sub> - 0.1	V
V <sub>IN</sub>	Input Voltage Swing (IN-to-/IN)	See Figure 1a.	0.1		1.7	V
V <sub>DIFF_IN</sub>	Differential Input Voltage Swing   IN - /IN	See Figure 1b.	0.2			V
$V_{T\_IN}$	Maximum Input Voltage (IN-to-V <sub>T</sub> )				1.28	V
V <sub>REF-AC</sub>	Output Reference Voltage		V <sub>CC</sub> - 1.3	V <sub>CC</sub> - 1.2	V <sub>CC</sub> - 1.1	V

#### Notes:

- 1. Permanent device damage may occur if absolute maximum ratings are exceeded. This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to absolute maximum ratings conditions for extended periods may affect device reliability.
- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- Package thermal resistance assumes exposed pad is soldered (or equivalent) to the devices most negative potential on the PCB. θ<sub>JA</sub> and ψ<sub>JB</sub> values are determined for a 4-layer board in still-air, unless otherwise stated.
- 4. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
- 5.  $V_{IH}$  (min) not lower than 1.2V.

# LVPECL Output DC Electrical Characteristics<sup>(5)</sup>

 $V_{CC}$  = 2.5V ±5% or 3.3V ±10%;  $R_L$  = 50 $\Omega$  to  $V_{CC}$ -2V;  $T_A$  = -40°C to +85°C, unless otherwise noted.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V <sub>OH</sub>	Output High Voltage (Q, /Q)		V <sub>CC</sub> -1.145		V <sub>CC</sub> -0.895	V
V <sub>OL</sub>	Output Low Voltage (Q, /Q)		V <sub>CC</sub> -1.945		V <sub>CC</sub> -1.695	V
V <sub>OUT</sub>	Output Voltage Swing (Q, /Q)	See Figure 1a.	400	800		mV
V <sub>DIFF-OUT</sub>	Differential Output Voltage Swing (Q, /Q)	See Figure 1b.	800	1600		mV

# LVTTL/CMOS DC Electrical Characteristics<sup>(5)</sup>

 $V_{CC}$  = 2.5V ±5% or 3.3V ±10%;  $T_A$  = -40°C to +85°C, unless otherwise noted.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V <sub>IH</sub>	Input High Voltage		2.0			V
V <sub>IL</sub>	Input Low Voltage				0.8	V
I <sub>IH</sub>	Input High Current	$V_{IN} = V_{CC}$			75	μA
I <sub>IL</sub>	Input Low Current	V <sub>IN</sub> = 0.5V	-300			μA

#### Notes:

5. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.

## AC Electrical Characteristics<sup>(6)</sup>

 $V_{CC}$  = 2.5V ±5% or 3.3V ±10%;  $T_A$  = -40°C to + 85°C,  $R_L$  = 50 $\Omega$  to  $V_{CC}$ -2V, unless otherwise stated.

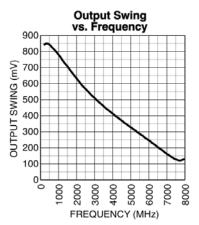
Symbol	Parameter	Condition	Min	Тур	Max	Units
f <sub>MAX</sub>	Maximum Operating Frequency	NRZ Data	2.5			Gbps
		Clock, V <sub>OUT</sub> > 400mV	2.5			GHz
t <sub>pd</sub>	Propagation Delay					
	IN-to-Q	V <sub>IN</sub> > 100mV	210	300	410	ps
	SEL-to-Q		100	300	500	ps
t <sub>pd</sub> Tempco	Differential Propagation Delay Temperature Coefficient			234		fs/°C
t <sub>SKEW</sub>	Output-to-Output	Note 7		9	20	ps
	Part-to-Part	Note 8			150	ps
t <sub>JITTER</sub>	Data					
	Random Jitter (RJ)	Note 9			1	ps <sub>RMS</sub>
	Deterministic Jitter (DJ)	Note 10			10	pspp
	Clock					
	Cycle-to-Cycle Jitter	Note 11			1	ps <sub>RMS</sub>
	Total Jitter (TJ)	Note 12			10	ps <sub>PP</sub>
	Crosstalk-induced Jitter (Adjacent Channel)	Note 13			0.7	ps <sub>RMS</sub>
t <sub>r,</sub> t <sub>f</sub>	Output Rise/Fall Time (20% to 80%)	At full output swing.	50	100	180	ps

#### Notes:

- High frequency AC electricals are guaranteed by design and characterization. 6.
- 7. Output-to-output skew is measured between outputs under identical input conditions.
- Part-to-part skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.
- Random jitter is measured with a K28.7 character pattern, measured at <f<sub>MAX</sub>.
- 10. Deterministic jitter is measured at 2.5Gbps with both K28.5 and 2<sup>23</sup>-1 PRBS pattern.
- Cycle-to-cycle jitter definition: the variation of periods between adjacent cycles,  $T_n T_{n-1}$  where T is the time between rising edges of the output signal.
- 12. Total jitter definition: with an ideal clock input of frequency < f<sub>MAX</sub>, no more than one output edge in 10<sup>12</sup> output edges will deviate by more than the specified peak-to-peak jitter value.
- 13. Crosstalk is measured at the output while applying two similar differential clock frequencies that are asynchronous with respect to each other at the inputs.

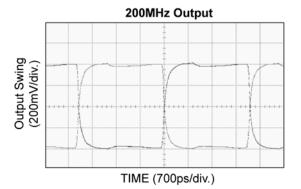
### **Typical Operating Characteristics**

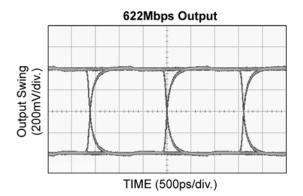
 $V_{CC}$  = 2.5V, GND = 0,  $V_{IN}$  = 100mV;  $T_A$  = -40°C to + 85°C,  $R_L$  = 50 $\Omega$  to  $V_{CC}$ -2V, unless otherwise stated.

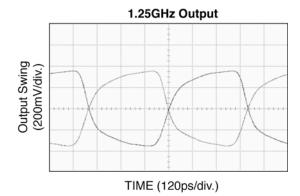


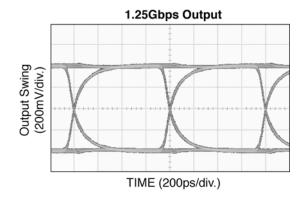
#### **Functional Characteristics**

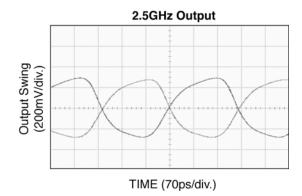
 $V_{CC}$  = 3.3V ±10%;  $T_A$  = -40°C to + 85°C,  $R_L$  = 50 $\Omega$  to  $V_{CC}$ -2V, unless otherwise stated.



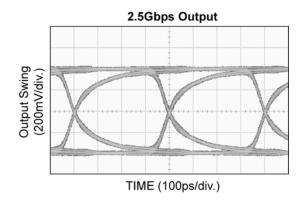








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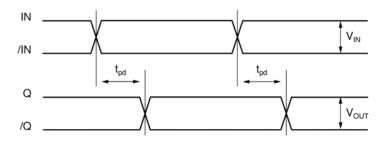
# **Single-Ended and Differential Swings**



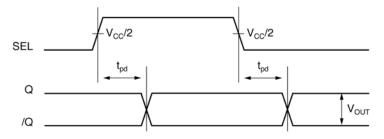
Figure 1a. Single-Ended Voltage Swing

Figure 1b. Differential Voltage Swing

### **Timing Diagram**



**IN-to-Q Timing Diagram** 



**SEL-to-Q Timing Diagram** 

### **Input and Output Stages**

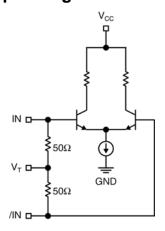


Figure 2a. Simplified Differential Input Stage

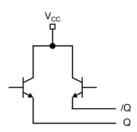


Figure 2b. PECL Output Stage

### **Input Interface Applications**

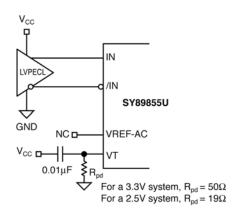


Figure 3a. LVPECL Interface (DC-Coupled)

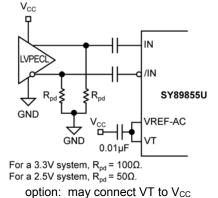


Figure 3b. LVPECL Interface (AC-Coupled)

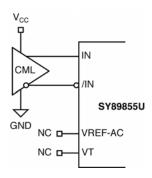


Figure 3c. CML Interface (DC-Coupled)

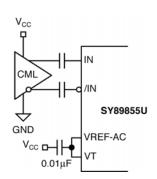


Figure 3d. CML Interface (AC-Coupled)

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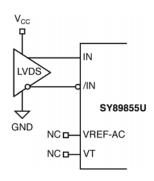
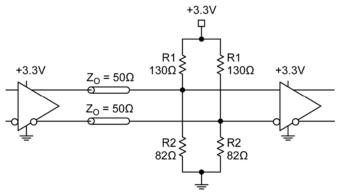


Figure 3e. LVDS Interface

### **Output Interface Applications**

LVPECL has high input impedance, very low output (open emitter) impedance, and small signal swing, which result in low EMI. LVPECL is ideal for driving  $50\Omega$  and  $100\Omega$  controlled impedance transmission lines. There are different techniques for terminating

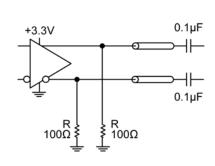
LVPECL outputs: parallel termination theveninequivalent, parallel termination (3-resistor), and ACcoupled termination. Unused output pairs may be left floating; however, single-ended outputs must be terminated or balanced.



Note:

For a 2.5V system, R1 =  $250\Omega$ , R2 =  $62.5\Omega$ .

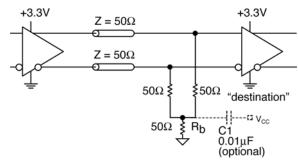
Figure 4a. Parallel Thevenin-Equivalent Termination



Note:

For a 2.5V system,  $R = 50\Omega$ .

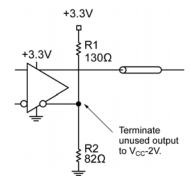
Figure 4c. AC-Coupled Termination



Note:

1. For a 2.5V system, Rb =  $19\Omega$ .

Figure 4b. Parallel Termination (3-Resistor)



Note:

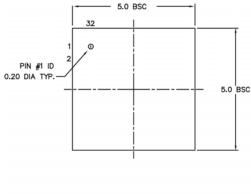
For a 2.5V system, R1 = 250 $\Omega$ , R2 = 62.5  $\Omega$ .

Figure 4d. Parallel Thevenin-Equivalent Termination

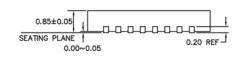
### **Related Product and Support Documentation**

Part Number	Function	Data Sheet Link
SY58029U	Ultra Precision Differential LVPECL 4 :1 MUX with 1 :2 Fanout Internal Termination	www.micrel.com/product-info/products/sy58029u.shtml.
HBW Solutions	New Products and Applications	www.micrel.com/product-info/products/solutions.shtml

## **Package Information**

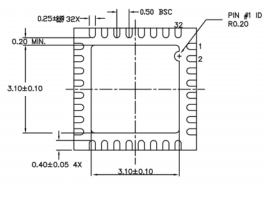






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SIDE VIEW



#### NOTE

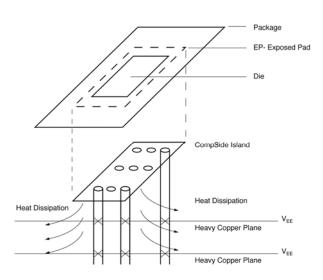
- ALL DIMENSIONS ARE IN MILLIMETERS.

  MAX. PACKAGE WARPAGE IS 0.05 mm.

  MAXIMUM ALLOWABE BURRS IS 0.076 mm IN ALL DIRECTIONS.

  PIN #1 ID ON TOP WILL BE LASER/INK MARKED.

32-Pin QFN



PCB Thermal Consideration for 32-Pin QFN Package (Always solder, or equivalent, the exposed pad to the PCB)

#### **Packages Notes:**

- Package meets Level 2 Moisture Sensitivity Classification.
- 2. All parts are dry-packed before shipment.
- Exposed pads must be soldered to a ground for proper thermal management.

August 2007 12 M9999-082907-C

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